

REVISIONS

LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
A	Add "Changes in accordance with NOR 5962-R295-92".	92-09-02	M. L. Poelking
B	Update to reflect latest changes in format and requirements. Editorial changes throughout. -les	01-02-05	Raymond Monnin
C	Update drawing to current requirements. Editorial changes throughout. - gap	08-07-23	Robert M. Heber

The original first sheet of this drawing has been replaced.

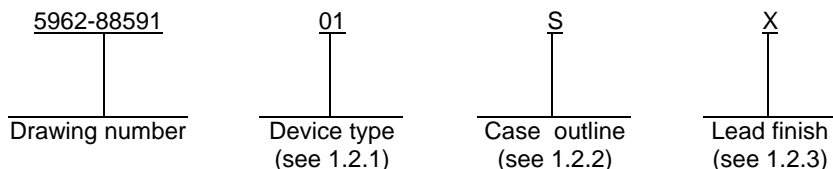
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OF SHEETS	SHEET	1	2	3	4	5	6	7	8	9	10	11	12							

PMIC N/A	PREPARED BY Christopher A. Rauch	<b>DEFENSE SUPPLY CENTER COLUMBUS</b> <b>COLUMBUS, OHIO 43218-3990</b> <a href="http://www.dsc.dla.mil">http://www.dsc.dla.mil</a>			
<b>STANDARD MICROCIRCUIT DRAWING</b>  THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE  AMSC N/A	CHECKED BY Raymond Monnin	MICROCIRCUIT, DIGITAL, BIPOLAR, ADVANCED LOW POWER SCHOTTKY TTL, INVERTING, OCTAL BUFFER AND LINE DRIVER WITH THREE- STATE OUTPUTS, MONOLITHIC SILICON			
	APPROVED BY Michael A. Frye				
	DRAWING APPROVAL DATE 88-04-27				
	REVISION LEVEL C	SIZE A	CAGE CODE <b>67268</b>	<b>5962-88591</b>	
		SHEET 1 OF 12			

1. SCOPE

1.1 Scope. This drawing describes device requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A.

1.2 Part or Identifying Number (PIN). The complete PIN is as shown in the following example:



1.2.1 Device type(s). The device type(s) identify the circuit function as follows:

<u>Device type</u>	<u>Generic number</u>	<u>Circuit function</u>
01	54ALS240	Inverting octal buffer and line driver with three-state output

1.2.2 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows:

<u>Outline letter</u>	<u>Descriptive designator</u>	<u>Terminals</u>	<u>Package style</u>
S	GDFF2-F20 or CDFF3-F20	20	Flat package

1.2.3 Lead finish. The lead finish is as specified in MIL-PRF-38535, appendix A.

1.3 Absolute maximum ratings. 1/

Supply voltage .....	-0.5 V dc to +7.0 V dc
Input voltage ( $V_{IN}$ ) .....	-1.2 V dc at -18mA to +7.0 V dc
Voltage applied to a disable 3-state output .....	5.5 V dc
Storage temperature range .....	-65°C to +150°C
Maximum power dissipation ( $P_D$ ) .....	137.5 mW 2/
Lead temperature (soldering, 10 seconds) .....	+300°C
Thermal resistance, junction-to-case ( $\theta_{JC}$ ) .....	See MIL-STD-1835
Junction temperature ( $T_J$ ) .....	+175°C

1.4 Recommended operating conditions.

Supply voltage range ( $V_{CC}$ ) .....	+4.5 V dc to +5.5 V dc
Minimum high-level input voltage ( $V_{IH}$ ) .....	+2.0 V dc
Maximum low level input voltage ( $V_{IL}$ ):	
$T_C = +125^\circ\text{C}$ .....	0.7 V dc
$T_C = -55^\circ\text{C}$ .....	0.8 V dc
$T_C = +25^\circ\text{C}$ .....	0.8 V dc
Case operating temperature range ( $T_C$ ) .....	-55°C to +125°C

1/ Stresses above the absolute maximum rating may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.  
 2/ Maximum power dissipation is defined as  $V_{CC} \times I_{CC}$ , and must withstand the added  $P_D$  due to short circuit test; e.g.,  $I_{OS}$ .

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2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.  
MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.  
MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at <http://assist.daps.dla.mil/quicksearch/> or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 Item requirements. The individual item requirements shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein. Product built to this drawing that is produced by a Qualified Manufacturer Listing (QML) certified and qualified manufacturer or a manufacturer who has been granted transitional certification to MIL-PRF-38535 may be processed as QML product in accordance with the manufacturers approved program plan and qualifying activity approval in accordance with MIL-PRF-38535. This QML flow as documented in the Quality Management (QM) plan may make modifications to the requirements herein. These modifications shall not affect form, fit, or function of the device. These modifications shall not affect the PIN as described herein. A "Q" or "QML" certification mark in accordance with MIL-PRF-38535 is required to identify when the QML flow option is used.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535, appendix A and herein.

3.2.1 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.

3.2.3 Truth table. The truth table shall be as specified on figure 2.

3.2.4 Logic diagram. The logic diagram shall be as specified on figure 3.

3.2.5 Switching waveforms and test circuit. The switching waveforms and test circuit shall be as specified on figure 4.

3.3 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full case operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.

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3.5 Marking. Marking shall be in accordance with MIL-PRF-38535, appendix A. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device.

3.5.1 Certification/compliance mark. A compliance indicator "C" shall be marked on all non-JAN devices built in compliance to MIL-PRF-38535, appendix A. The compliance indicator "C" shall be replaced with a "Q" or "QML" certification mark in accordance with MIL-PRF-38535 to identify when the QML flow option is used.

3.6 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-PRF-38535, appendix A and the requirements herein.

3.7 Certificate of conformance. A certificate of conformance as required in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.

3.8 Notification of change. Notification of change to DSCC-VA shall be required for any change that affects this drawing.

3.9 Verification and review. DSCC, DSCC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

4. VERIFICATION

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.

4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:

a. Burn-in test, method 1015 of MIL-STD-883.

(1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.

(2)  $T_A = +125^\circ\text{C}$ , minimum.

b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

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TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions <u>1/</u> -55°C ≤ T <sub>C</sub> ≤ +125°C unless otherwise specified	Group A subgroups	Limits		Unit
				Min	Max	
High level output voltage	V <sub>OH1</sub>	V <sub>IH</sub> = +2.0 V, V <sub>CC</sub> = +4.5 V, I <sub>OH</sub> = -12 mA <u>2/</u>	V <sub>IL</sub> = 0.8 V	1, 3	2.0	V
			V <sub>IL</sub> = 0.7 V	2		
	V <sub>OH2</sub>	V <sub>IH</sub> = +2.0 V, V <sub>CC</sub> = +4.5 V, I <sub>OH</sub> = -3 mA <u>2/</u>	V <sub>IL</sub> = 0.8 V	1, 3	2.4	V
			V <sub>IL</sub> = 0.7 V	2		
	V <sub>OH3</sub>	V <sub>IH</sub> = +2.0 V, V <sub>CC</sub> = +4.5 V, I <sub>OH</sub> = -0.4 mA <u>2/</u>	V <sub>IL</sub> = 0.8 V	1, 3	2.5	V
			V <sub>IL</sub> = 0.7 V	2		
Low level output voltage	V <sub>OL</sub>	I <sub>OL</sub> = +12 mA V <sub>CC</sub> = +4.5 V, V <sub>IH</sub> = +2.0 V <u>2/</u>	V <sub>IL</sub> = 0.8 V	1, 3	0.4	V
			V <sub>IL</sub> = 0.7 V	2		
Input clamp voltage	V <sub>IC</sub>	I <sub>IN</sub> = -18 mA, V <sub>CC</sub> = +4.5 V	1, 2, 3		-1.2	V
Off-state output current	I <sub>OZH</sub>	V <sub>CC</sub> = +5.5 V, V <sub>IH</sub> = +2.0 V, V <sub>OUT</sub> = +2.7 V	1, 2, 3		20	μA
	I <sub>OZL</sub>	V <sub>CC</sub> = +5.5 V, V <sub>IH</sub> = +2.0 V, V <sub>OUT</sub> = +0.4 V	1, 2, 3		-20	
High level input current	I <sub>IH1</sub>	V <sub>CC</sub> = +5.5 V, V <sub>IN</sub> = +2.7 V, All other inputs = 0.0 V	1, 2, 3		20	μA
	I <sub>IH2</sub>	V <sub>CC</sub> = +5.5 V, V <sub>IN</sub> = +7.0 V, All other inputs = 0.0 V	1, 2, 3		0.1	
Low level input current	I <sub>IL</sub>	V <sub>CC</sub> = +5.5 V, V <sub>IN</sub> = 0.4 V, All other inputs = 4.5 V	1, 2, 3		-0.1	mA
Output current	I <sub>O</sub>	V <sub>CC</sub> = +5.5 V, V <sub>OUT</sub> = 2.25 V <u>3/</u>	1, 2, 3	-20	-112	mA
Supply current	I <sub>CCH</sub>	V <sub>CC</sub> = +5.5 V	1, 2, 3		11	mA
	I <sub>CCL</sub>		1, 2, 3		23	
Supply current disabled	I <sub>CCZ</sub>		1, 2, 3		25	mA

See footnotes at end of table.

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TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions -55°C ≤ T <sub>C</sub> ≤ +125°C 1/ unless otherwise specified	Group A subgroups	Limits		Unit
				Min	Max	
Functional tests		See 4.3.1c 4/	7, 8			
Propagation delay time, A to Y	t <sub>PLH</sub>	V <sub>CC</sub> = 4.5 V to 5.5 V, C <sub>L</sub> = 50 pF, 5/ R <sub>L1</sub> = 500 Ω ±5% , R <sub>L2</sub> = 500 Ω ±5% See figure 4	9, 10, 11	2	12	ns
	t <sub>PHL</sub>		9, 10, 11	2	9	ns
Output enable time, $\bar{G}$ to Y	t <sub>PZL</sub>		9, 10, 11	5	18	ns
	t <sub>PZH</sub>		9, 10, 11	4	15	ns
Output disable time, $\bar{G}$ to Y	t <sub>PLZ</sub>		9, 10, 11	3	15	ns
	t <sub>PHZ</sub>		9, 10, 11	1	10	ns

- 1/ Unused inputs that do not directly control the pin under test must be ≥ 2.5 V or ≤ 0.4 V. No unused inputs shall exceed 5.5 V or go less than 0.0 V. No input shall be floated.
- 2/ All outputs must be tested. In the case where only one input at V<sub>IL</sub> maximum or V<sub>IH</sub> minimum produces the proper output state, the test must be performed with each input being selected as the V<sub>IL</sub> maximum or V<sub>IH</sub> minimum input.
- 3/ The output conditions have been chosen to produce a current that closely approximates on half of the true short circuit output current, I<sub>OS</sub>. Not more than one output shall be tested at one time, and the duration of the test condition shall not exceed one second.
- 4/ Function tests shall be conducted at input test conditions of GND ≤ V<sub>IL</sub> ≤ V<sub>OL</sub> and V<sub>OH</sub> ≤ V<sub>IH</sub> ≤ V<sub>CC</sub>.
- 5/ Propagation delay limits are base on single output switching. Unused inputs = 3.5 V or ≤ 0.3 V.

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Device type 01	
Case outline S	
Terminal number	Terminal symbol
1	$\bar{G}$
2	1A1
3	2Y4
4	1A2
5	2Y3
6	1A3
7	2Y2
8	1A4
9	2Y1
10	GND
11	2A1
12	1Y4
13	2A2
14	1Y3
15	2A3
16	1Y2
17	2A4
18	1Y1
19	2G
20	V <sub>CC</sub>

FIGURE 1. Terminal connections.

Inputs		Output
$\bar{G}$	A	Y
H	X	Z
L	L	L
L	H	H

H = High level  
L = Low level  
X = Irrelevant  
Z = High impedance

FIGURE 2. Truth table.

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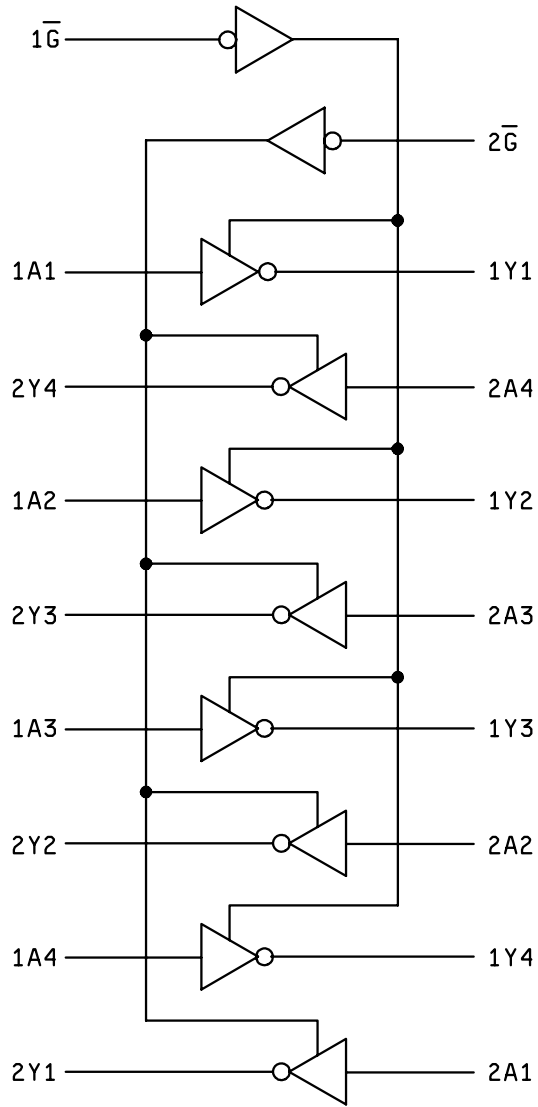
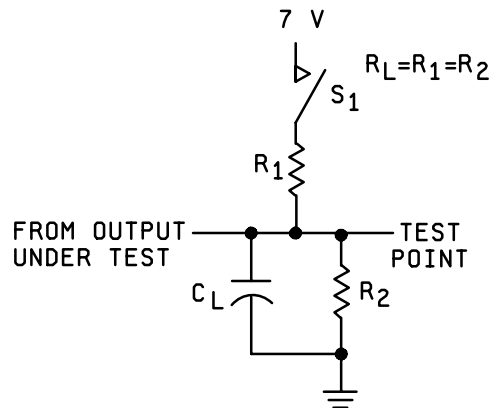
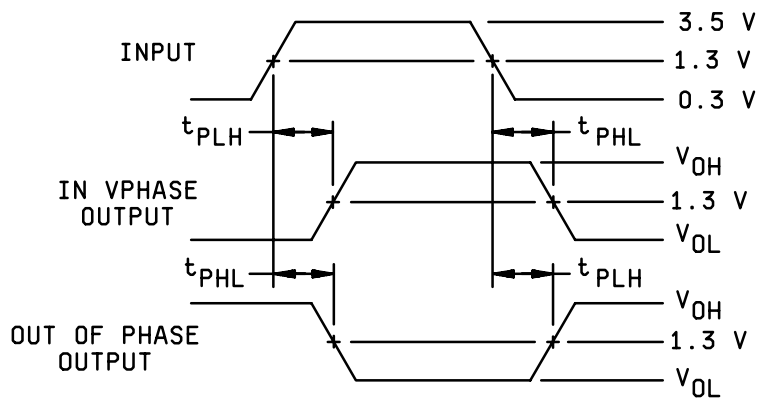


FIGURE 3. Logic diagram.

<b>STANDARD MICROCIRCUIT DRAWING</b> DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990	SIZE <b>A</b>		<b>5962-88591</b>
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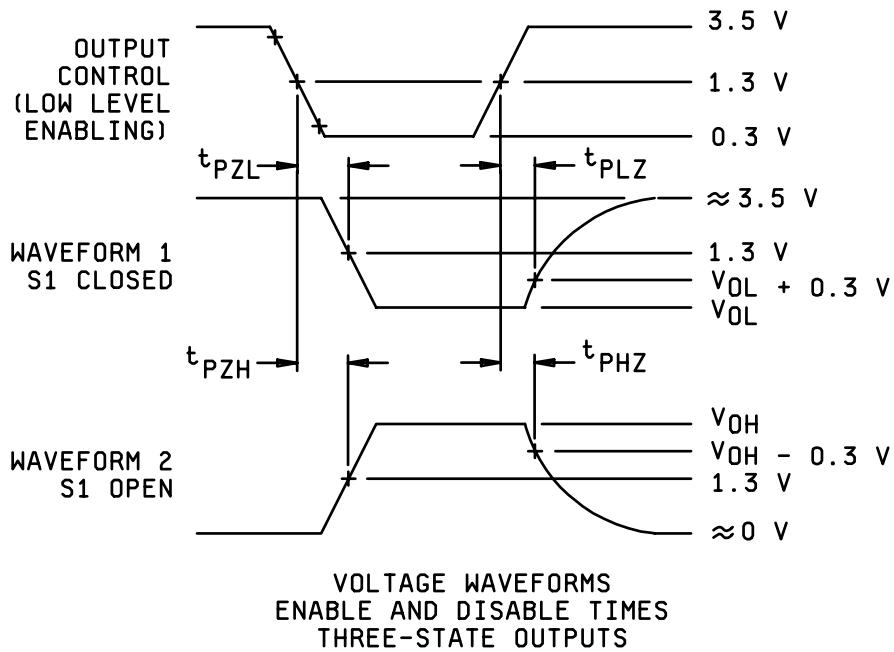
LOAD CIRCUIT FOR  
THREE-STATE OUTPUTS



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES

FIGURE 4. Switching waveforms and test circuit.

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NOTES:

1.  $C_L$  includes probe and jig capacitance.
2. All input pulses have the following characteristics:  $PRR \leq 10$  MHz, duty cycle = 50%,  $t_r = 3$  ns  $\pm$  1 ns,  $t_f = 3$  ns  $\pm$  1 ns.
3. The outputs are measured one at a time with one input transition per measurement.
4. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.  
Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
5. When measuring propagation delay times of three-state outputs, switch S1 is open.

FIGURE 4. Switching waveforms and test circuit - Continued.

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TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)
Interim electrical parameters (method 5004)	- - -
Final electrical test parameters (method 5004)	1*, 2, 3, 7, 8, 9, 10, 11
Group A test requirements (method 5005)	1, 2, 3, 7, 8, 9, 10, 11
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3

\* PDA applies to subgroup 1.

4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

4.3.1 Group A inspection.

- a. Tests shall be as specified in table II herein.
- b. Subgroups 4, 5, and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
- c. Subgroups 7 and 8 shall include verification of the truth table.

4.3.2 Groups C and D inspections.

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test conditions, method 1005 of MIL-STD-883.
  - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
  - (2)  $T_A = +125^{\circ}\text{C}$ , minimum.
  - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

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5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535, appendix A.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.3 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.

6.4 Record of users. Military and industrial users shall inform Defense Supply Center Columbus (DSCC) when a system application requires configuration control and the applicable SMD. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0544.

6.5 Comments. Comments on this drawing should be directed to DSCC-VA, Columbus, Ohio 43218-3990, or telephone (614) 692-0547.

6.6 Approved sources of supply. Approved sources of supply are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DSCC-VA.

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STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 08-07-23

Approved sources of supply for SMD 5962-88591 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535. DSCC maintains an online database of all current sources of supply at <http://www.dscclia.mil/Programs/Smcr/>.

Standard microcircuit drawing PIN <u>1/</u>	Vendor CAGE number	Vendor similar PIN <u>2/</u>	Reference military specification part number
5962-8859101SA	01295	SNJ54ALS240AW	M38510/38301BSA
	<u>3/</u>	54ALS240AW/883	
	<u>3/</u>	54ALS240A/BSA	

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- 2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- 3/ Not available from an approved source of supply.

Vendor CAGE  
number

01295

Vendor name  
and address

Texas Instruments, Inc.  
Semiconductor Group  
8505 Forest Lane  
PO Box 660199  
Dallas, TX 75243

POC U.S. Highway 75 South  
P.O. Box 84, M/S 853  
Sherman, TX 75090-9493

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